

### TK39N60W-VB Datasheet

# N-Channel 600V (D-S) Super Junction Power MOSFET

| PRODUCT SUMMA                              | RY                     |       |
|--|------------------------|-------|
| V <sub>DS</sub> (V) at T <sub>J</sub> max. | 600                    | )     |
| R <sub>DS(on)</sub> at 25 °C (Ω)           | V <sub>GS</sub> = 10 V | 0.060 |

#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)

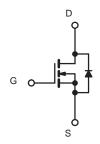
#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- - High-intensity discharge (HID)
  - Fluorescent ballast lighting









N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted) |                         |                         |                                   |             |                                       |  |
|---|-------------------------|-------------------------|-----------------------------------|-------------|---------------------------------------|--|
| PARAMETER   |                         |                         | SYMBOL                            | LIMIT       | UNIT                                  |  |
| Drain-Source Voltage  |                         |                         | $V_{DS}$                          | 600         | V                                     |  |
| Gate-Source Voltage   |                         |                         | $V_{GS}$                          | ± 30        | \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ |  |
| Continuous Drain Current (T <sub>J</sub> = 150 °C)                        | V <sub>GS</sub> at 10 V | T <sub>C</sub> = 25 °C  | I <sub>D</sub>                    | 47          |                                       |  |
|   |                         | T <sub>C</sub> = 100 °C |                                   | 29          | Α                                     |  |
| Pulsed Drain Current <sup>a</sup>   |                         |                         | I <sub>DM</sub>                   | 140         |                                       |  |
| Linear Derating Factor  |                         |                         |                                   | 1.67        | W/°C                                  |  |
| Single Pulse Avalanche Energy b   |                         |                         | E <sub>AS</sub>                   | 850         | mJ                                    |  |
| Maximum Power Dissipation   |                         |                         | P <sub>D</sub>                    | 510         | W                                     |  |
| Operating Junction and Storage Temperature Range                          |                         |                         | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150 | °C                                    |  |
| Drain-Source Voltage Slope  | T <sub>J</sub> = 125 °C |                         | dV/dt 50                          |             | \//                                   |  |
| Reverse Diode dV/dt d   |                         |                         | uv/ut                             | 15          | V/ns                                  |  |
| Soldering Recommendations (Peak Temperature) c                            | for                     | 10 s                    |                                   | 260         | °C                                    |  |

- a. Repetitive rating; pulse width limited by maximum junction temperature. b.  $V_{DD}=100$  V, starting  $T_J=25$  °C, L = 30mH,  $R_g=25$   $\Omega$ ,  $I_{AS}=24$ A.

- c. 1.6 mm from case. d.  $I_{SD} \le I_D$ , dl/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C.



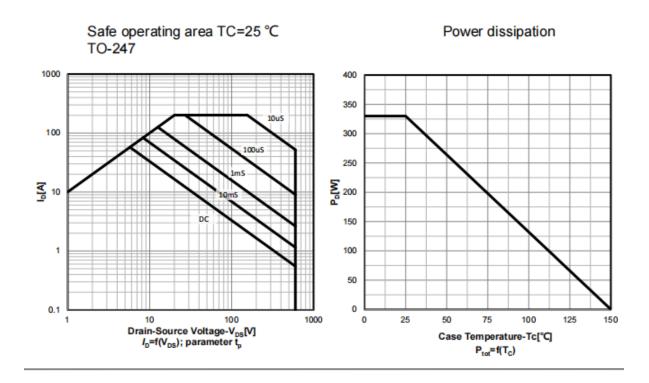
| THERMAL RESISTANCE RATI          | NGS               |      |      |      |
|----------------------------------|-------------------|------|------|------|
| PARAMETER                        | SYMBOL            | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient      | R <sub>thJA</sub> | -    | 62   | °C/W |
| Maximum Junction-to-Case (Drain) | $R_{thJC}$        | -    | 0.38 | C/VV |

| PARAMETER   | SYMBOL                | TES  | T CONDITIONS   | MIN. | TYP.  | MAX.  | UNIT |
|---|-----------------------|--|--|------|-------|-------|------|
| Static  |                       | -  |  |      | •     |       |      |
| Drain-Source Breakdown Voltage                            | V <sub>DS</sub>       | V <sub>GS</sub> :  | = 0 V, I <sub>D</sub> = 1 mA                         | 600  | -     | -     | V    |
| V <sub>DS</sub> Temperature Coefficient                   | $\Delta V_{DS}/T_{J}$ | Reference  | e to 25 °C, I <sub>D</sub> = 1 mA                    | -    | 0.70  | -     | V/°C |
| Gate-Source Threshold Voltage (N)                         | V <sub>GS(th)</sub>   | V <sub>DS</sub> =  | = V <sub>GS</sub> , I <sub>D</sub> = 250 μA          | 2.5  | -     | 4.5   | V    |
|   |                       |  | V <sub>GS</sub> = ± 20 V                             | -    | -     | ± 100 | nA   |
| Gate-Source Leakage                                       | I <sub>GSS</sub>      | _  | V <sub>GS</sub> = ± 30 V                             | -    | -     | ± 1   | μA   |
|   |                       | V <sub>DS</sub> =  | = 600V, V <sub>GS</sub> = 0 V                        | -    | -     | 1     |      |
| Zero Gate Voltage Drain Current                           | $I_{DSS}$             |  | V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C    | -    | -     | 100   | μA   |
| Drain-Source On-State Resistance                          | R <sub>DS(on)</sub>   | V <sub>GS</sub> = 10 V   | I <sub>D</sub> =16A                                  | -    | 0.060 | -     | Ω    |
| Forward Transconductance                                  | 9fs                   | V <sub>DS</sub>  | = 30 V, I <sub>D</sub> = 16 A                        | -    | 5.6   | -     | S    |
| Dynamic   |                       |  |  |      |       |       |      |
| Input Capacitance   | C <sub>iss</sub>      | V0V  |  | -    | 4900  | -     | pF   |
| Output Capacitance  | Coss                  | 1  | $V_{GS} = 0 \text{ V},$<br>$V_{DS} = 100 \text{ V},$ |      | 330   | -     |      |
| Reverse Transfer Capacitance                              | C <sub>rss</sub>      | f = 1 MHz  |  | -    | 4     | -     |      |
| Effective Output Capacitance, Energy Related <sup>a</sup> | C <sub>o(er)</sub>    | - V <sub>DS</sub> = 0 V to 520 V, V <sub>GS</sub> = 0 V  |  | -    | 63    | -     |      |
| Effective Output Capacitance, Time Related <sup>b</sup>   | C <sub>o(tr)</sub>    |  |  | -    | 213   | -     |      |
| Total Gate Charge   | Qg                    |  |  | -    | 370   | -     |      |
| Gate-Source Charge  | Q <sub>gs</sub>       | V <sub>GS</sub> = 10 V   | $I_D = 20 \text{ A}, V_{DS} = 520 \text{ V}$         | -    | 3 9   | -     | nC   |
| Gate-Drain Charge   | $Q_{gd}$              |  |  | ı    | 4 7   | -     |      |
| Turn-On Delay Time  | $t_{d(on)}$           |  |  | ı    | 18    | 25    |      |
| Rise Time   | t <sub>r</sub>        | V <sub>DD</sub> = 520 V, I <sub>D</sub> = 20A,   |  | ı    | 24    | 55    | ns   |
| Turn-Off Delay Time                                       | t <sub>d(off)</sub>   |  |  | i    | 8 0   | ı     |      |
| Fall Time   | t <sub>f</sub>        | $V_{GS}$ = 10 V, $R_g$ = 9.1 $\Omega$  |  | •    | 1 2   | -     |      |
| Gate Input Resistance                                     | R <sub>g</sub>        | f = 1 MHz, open drain  |  | -    | 0.8   | -     | Ω    |
| Drain-Source Body Diode Characteristic                    | s                     |  |  |      |       |       |      |
| Continuous Source-Drain Diode Current                     | I <sub>S</sub>        | MOSFET symbol showing the integral reverse p - n junction diode  |  | -    | -     | 47    |      |
| Pulsed Diode Forward Current                              | I <sub>SM</sub>       |  |  | -    | -     | 140   | - A  |
| Diode Forward Voltage                                     | V <sub>SD</sub>       | T <sub>J</sub> = 25 °  | C, I <sub>S</sub> = 8 A, V <sub>GS</sub> = 0 V       | -    | -     | 1.5   | V    |
| Reverse Recovery Time                                     | t <sub>rr</sub>       |  |  | -    | 520   | -     | ns   |
| Reverse Recovery Charge                                   | Q <sub>rr</sub>       | T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 8 A,<br>dl/dt = 100 A/ $\mu$ s, V <sub>R</sub> = 400 V |  | -    | 5.8   | -     | μC   |
| Reverse Recovery Current                                  | I <sub>RRM</sub>      |  |  | _    | 4 5   | _     | A    |

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .





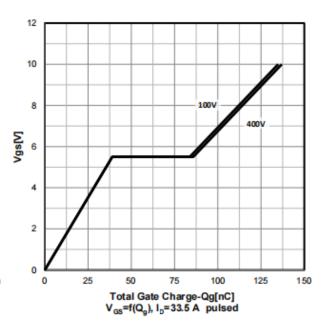
Typ. output characteristics  $T_i$ =25  $^{\circ}$ C Transfer characteristics 300 300 25°C . I<sub>D</sub>, Drain Current [A] Drain Current [A] 200 150°C -0 5 10 0 15 20 0 2 10 12 V<sub>GS</sub>, Gate-Source Voltage [V] V<sub>DS</sub>, Drain to Source Voltage [V]



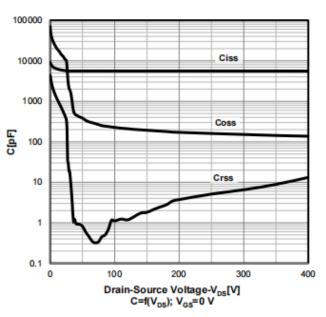
Typ. drain-source on-state resistance

80
70
60
60
40
30
20
0 15 30 45 60 75 90
Drain-Source Current-I<sub>D</sub>[A]
R<sub>DS</sub>(on)=f(I<sub>D</sub>); parameter:V<sub>GS</sub>

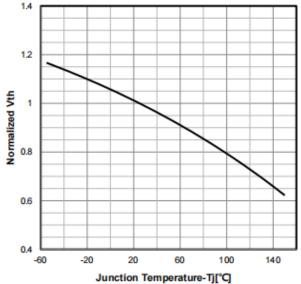
Typ. gate charge characteristics



Typ. capacitances

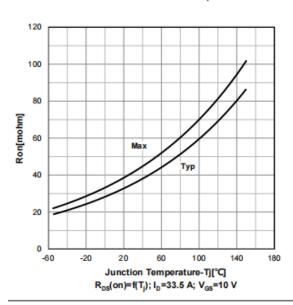


### Normalized $V_{\text{GS(th)}}$ characteristics

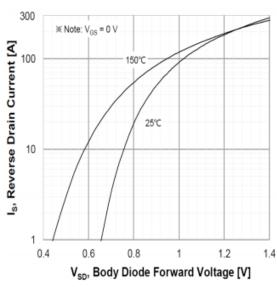




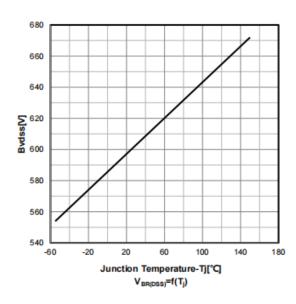
#### On-resistance vs temperature



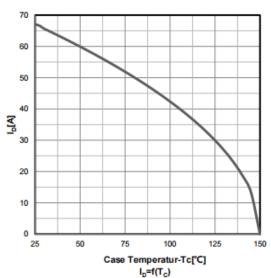
#### Forward characteristics of reverse diode



#### Drain-source breakdown voltage



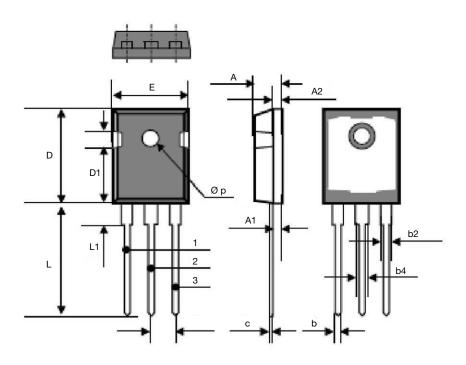
#### Drain current vs temperature



服务热线:400-655-8788 5



# TO-247



| DIM. | MILLIN | METERS | INCHES    |       |  |
|------|--------|--------|-----------|-------|--|
|      | MIN.   | MAX.   | MIN.      | MAX.  |  |
| А    | 4.70   | 5.31   | 0.185     | 0.209 |  |
| A1   | 2.21   | 2.59   | 0.087     | 0.102 |  |
| A2   | 1.50   | 2.49   | 0.059     | 0.098 |  |
| b    | 0.99   | 1.40   | 0.039     | 0.055 |  |
| b2   | 1.65   | 2.41   | 0.065     | 0.095 |  |
| b4   | 2.59   | 3.43   | 0.102     | 0.135 |  |
| С    | 0.61   | BSC    | 0.024 BSC |       |  |
| D    | 20.80  | 21.46  | 0.819     | 0.845 |  |
| D1   | 3.68   | 5.49   | 0.145     | 0.216 |  |
| (e)  | 5.46   | BSC    | 0.215     | BSC   |  |
| E    | 15.49  | 16.26  | 0.610     | 0.640 |  |
| L    | 19.81  | 20.32  | 0.780     | 0.800 |  |
| L1   | 4.06   | 4.50   | 0.160     | 0.177 |  |
| Øр   | 3.51   | 3.66   | 0.138     | 0.144 |  |



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